

VERSION WITH MARKINGS TO SHOW CHANGES MADE

In the claims:

Claim 13 has been amended as follows, and claims 19-28 have added:

13 (amended). A multi-chip package type semiconductor device, comprising:

a first semiconductor chip having a first terminal pad and a conductive relay pad, the conductive relay pad including a first area and a second area;

a second semiconductor chip, which is placed on the first semiconductor chip, the second semiconductor chip having a second terminal pad, connected to the conductive relay pad in the second area;

a first internal terminal connected to the first terminal pad; and

a second internal terminal connected to the conductive relay pad in the first area.